ENVIRONMENTAL AND PACKAGE TESTING DATA FOR TO-251/252 AND REVERSE TO-252 (DPAK)					
Stress	**Sample Size**	**Device Hr./Cyc**	**Condition**	**Total Fails**	**Fail Percentage**
85/85	1,050	744,704	85°C, 85%RH	0	0.00
BOND INT	2,800	1,400,000	200°C + N2	0	0.00
HAST	47,598	2,701,050	130°C, 85%RH	0	0.00
Power Cycle	3,700	36,871,748	DELTA Tj=100	0	0.00
Pressure Pot	11,788	1,200,288	121°, 15 PSIG	0	0.00
Solder DUNK	2,630	7,890	260°C, 10SEC	0	0.00
Solderability	1,547	15,616	883 M2003	0	0.00
Temp Cycle	14,008	280,000	−65°C−150°C	0	0.00
Thermal Shock	76,551	4,263.024	−60°C−150°C	0	0.00